TGP2000PT
Thermally Conductive Gap Pad

BENEFITS AND FEATURES

- High thermal performance
- Ultra-soft
- High compressibility
- Excellent gap-filling capability
- Natural tacky
- Extreme low oil bleeding

TYPICAL APPLICATIONS

- EV battery & charging station
- Automotive electronics
- Power devices & modules
- Telecommunications & network servers

OVERVIEW

Honeywell TGP2000PT Thermally Conductive Gap Pad provides high thermal performance and excellent thermal reliability. The material's putty-like design enables excellent gap-filling capability for applications with large dimensional variances. Special surface reinforcement enables easier handling for operators during high volume assembly. The product is naturally tacky and requires no additional adhesive to mate to heat source and heat sink. Products are available in thicknesses ranging from 0.5mm to 5.0mm.

STORAGE & USE

Shelf life 12 months at 0-35°C, <65%RH

Property	TGP2000PT	Test Method
Color	Pink	Visual
Thickness (mm)*	0.5-5	ASTM D374
Specific Gravity	2.9	ASTM D792
Hardness (Shore00)	5	ASTM D2240
Thermal Conductivity (W/m·K)	2.5	ASTM D5470
Thermal Impedance ($°C·in^2/W$)(1mm@10psi) (Typical Value)	0.65	ASTM D5470
Dielectric Constant@1MHz	6	ASTM D150
Volume Resistivity (ohm·cm)	4×10^{13}	ASTM D257
Flammability Rating	V-0	UL94

* Thickness range: 0.5-5.0mm with 0.25mm incremental
Thickness Tolerance: >=1mm, ±10%
0.5-1mm, ±0.1mm

Honeywell Electronic Materials

USA: 1-509-252-2102
Mainland China: 400-840-2233
Germany: 49-5137-999-9199
Japan: 81-3-6730-7092
Korea: 82-2-3483-5076
Singapore: 65-6580-3593
Taiwan: 886-3-6580300 ext.312
www.electronicmaterials.com